



BOARD LEVEL COOLING - 3750

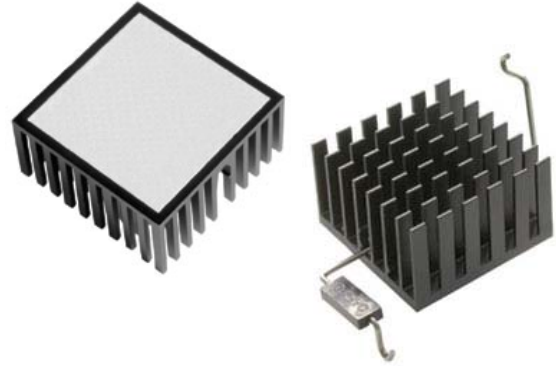
3750 is a series of square pin fin board level heat sinks designed to cool BGA and FPGA devices. Representative Image Only.

ORDERING INFORMATION

| Part Number | Device Type |
|---------------|-------------|
| 375024B00032G | BGA, FPGA |
| 375024B60024G | BGA, FPGA |

HEAT SINK DETAILS

| Property | Details |
|--|--|
| Material | Aluminum |
| Finish | Black Anodize |
| Device Attachment Options: 375024B00032G | Tape |
| Device Attachment Options: 375024B60024G | Solder Anchor Clip |
| Thermal Interface Material: 375024B00032G | T411 Chomerics Tape for All Surfaces |
| Thermal Interface Material: 375024B60024G | T766 Chomerics Phase Change for All Surfaces |

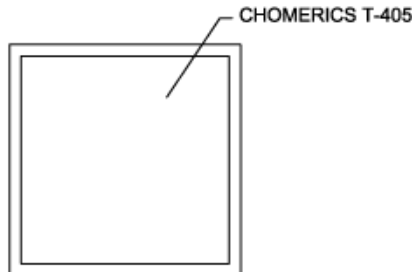
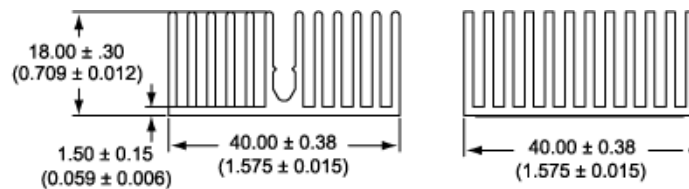


| Property | Details |
|------------------------------|----------------------|
| Heat Sink Width (mm) | 40.00 |
| Heat Sink Length (mm) | 40.00 |
| Heat Sink Height (mm) | 18.00 |
| Heat Sink Mounting Direction | Horizontal, Vertical |

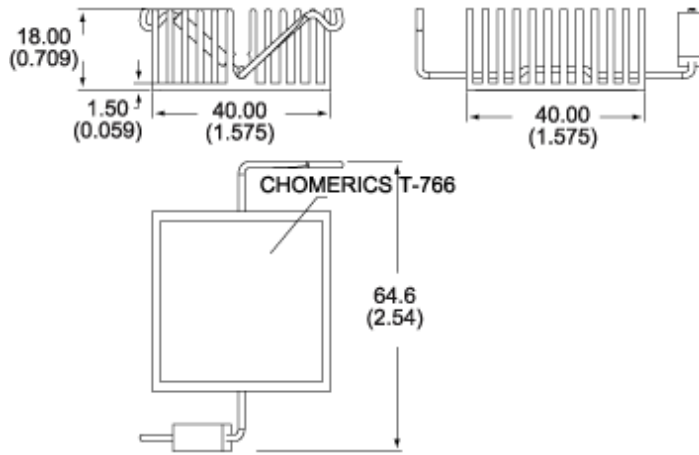
MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)

Part Number: 375024B00032G



Part Number: 375024B60024G



Mounting Details:

